

LAMP APPLICATION (PB FREE SOLDERJING)

Apply to LAMP (DIP) SERIES.

Description:

(1) Manual soldering (Solder Iron)

- (1.1) Temperature at tip of the iron: 350°C Max.
- (1.2) It's banned to load any stress on the resin during soldering.
- (1.3) Soldering time: 3sec.Max.(one time only.)
- (1.4) Leave 3mm of minimum distance from the base of the epoxy.

(2) Dip Soldering (Wave Soldering-Solder Bath)

- (2.1) Leave 3mm of minimum distance from the base of the epoxy.
Soldering beyond the base of the tie bar (stand off) is recommended.
- (2.2) When soldering, do not put stress on the LEDs during heating.
- (2.3) Cutting the lead frames at high temperatures may cause LED failure.
- (2.4) Never take next process until the component is cooled down to room temperature after reflow.
- (2.5) After soldering, do not warp the circuit board.
- (2.6) The recommended dip soldering profile is the following.

